

TITLE OF THE INVENTION

STACKED SEMICONDUCTOR DEVICE AND METHOD OF  
PRODUCING THE SAME

CROSS REFERENCE TO RELATED APPLICATION

This application is a division of Ser. No.  
09/940,625, filed August 29, 2001, *now Patent Number 6,621,169*

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention generally relates to semiconductor devices and methods of producing the semiconductor devices, and, more particularly, to a stacked semiconductor device having a plurality of semiconductor chips stacked as one package and a method of producing such a stacked semiconductor device.

2. Description of the Related Art

In recent years, portable electronic devices such as mobile telephones and non-volatile memory media such as IC memory cards have been becoming smaller and smaller. Along with this trend, there have been demands for devices and memory media having a smaller number of components and a smaller size. Accordingly, it is desired to develop a technique of effectively packaging semiconductor chips that are main components constituting those electronic devices and memory media. Examples of such packages that satisfy the above demands include a chip scale package (CSP) that is almost as small as a semiconductor chip and a multi-chip package (MCP) that accommodates a plurality of semiconductor chips in one package.

The CSP or MCP is realized by stacking and turning a plurality of semiconductor chips into one package. This technique is represented by a stacked multi-chip package (S-MCP).

FIG. 1 shows the structure of a conventional S-MCP in which two semiconductor chips are stacked. As shown in FIG. 1, a semiconductor chip 2 is mounted on a substrate 4,